Title (en)

HIGHLY HEAT CONDUCTIVE ALUMINUM ALLOY FOR DIE CASTING, ALUMINUM ALLOY DIE CAST PRODUCT USING SAME, AND HEATSINK USING SAME

Title (de)

SEHR WÄRMELEITFÄHIGE ALUMINIUMLEGIERUNG ZUM STRANGGIESSEN, ALUMINIUMLEGIERUNGSSTRANGGUSSPRODUKT DAMIT UND KÜHLKÖRPER DAMIT

Title (fr)

ALLIAGE D'ALUMINIUM À HAUTE CONDUCTIVITÉ THERMIQUE POUR LA COULÉE SOUS PRESSION, PRODUIT COULÉ SOUS PRESSION EN ALLIAGE D'ALUMINIUM L'UTILISANT, ET DISSIPATEUR DE CHALEUR L'UTILISANT

Publication

EP 2871250 A4 20151014 (EN)

Application

EP 12883779 A 20120831

Priority

JP 2012005531 W 20120831

Abstract (en)

[origin: EP2871250A1] A highly heat conductive aluminum alloy for die casting, having excellent castability and capable of obtaining a heat conductivity not lower than 170 W/(m·K) without having heat treatment performed thereon, and an aluminum alloy die cast product using the same alloy have been developed. Specifically, the highly heat conductive aluminum alloy for die casting contains Cu by not more than 2.30 wt%, Si by not more than 1.50 wt%, and Fe by 1.20 to 2.60 wt%, and a remaining portion thereof is Al and unavoidable impurities.

IPC 8 full level

C22C 21/00 (2006.01); **C22C 21/12** (2006.01); **C22C 21/14** (2006.01)

CPC (source: CN EP KR)

C22C 21/00 (2013.01 - CN EP); **C22C 21/02** (2013.01 - CN); **C22C 21/12** (2013.01 - CN EP); **C22C 21/14** (2013.01 - CN EP KR)

Citation (search report)

- [X] WO 2012036181 A1 20120322 - FURUKAWA SKY ALUMINUM CORP [JP], et al
- [X] JP 2005163077 A 20050623 - MITSUBISHI ALUMINIUM
- [X] JP H03100145 A 19910425 - SKY ALUMINIUM
- See references of WO 2014033791A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2871250 A1 20150513; **EP 2871250 A4 20151014**; **EP 2871250 B1 20160720**; CN 104619871 A 20150513; CN 104619871 B 20161214; JP 5301750 B1 20130925; JP WO2014033791 A1 20160808; KR 101924319 B1 20181203; KR 20150046014 A 20150429; PH 12015500207 A1 20150316; PH 12015500207 B1 20150316; PL 2871250 T3 20170131; WO 2014033791 A1 20140306

DOCDB simple family (application)

EP 12883779 A 20120831; CN 201280075573 A 20120831; JP 2012005531 W 20120831; JP 2013514266 A 20120831; KR 20157002646 A 20120831; PH 12015500207 A 20150130; PL 12883779 T 20120831